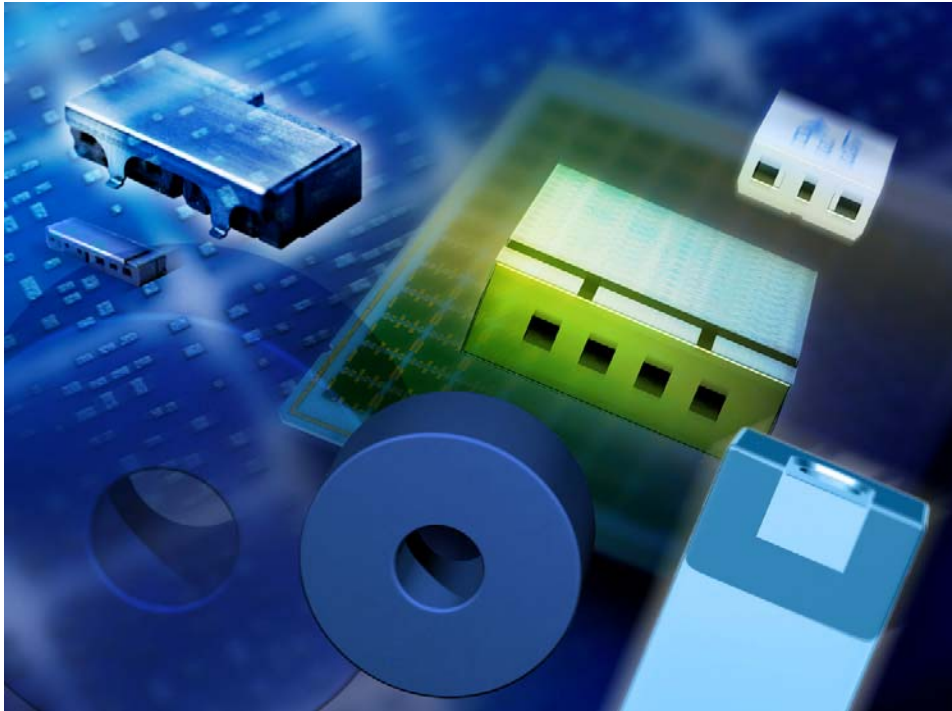


Data Sheet



Features

- SMD filter consisting of coupled resonators with stepped impedances
- extreme low losses
- high attenuations at GSM (900, 1800) and UMTS bands
- high attenuation a 2 times center frequency
- $(\text{NdBa})\text{TiO}_3$ ($\epsilon_r = 88 / TC_f = 0 \pm 10 \text{ ppm/K}$) with a coating of copper ($10\mu\text{m}$) and tin ($>5\mu\text{m}$)
- Excellent reflow solderability, no migration effect due to copper/tin metallization

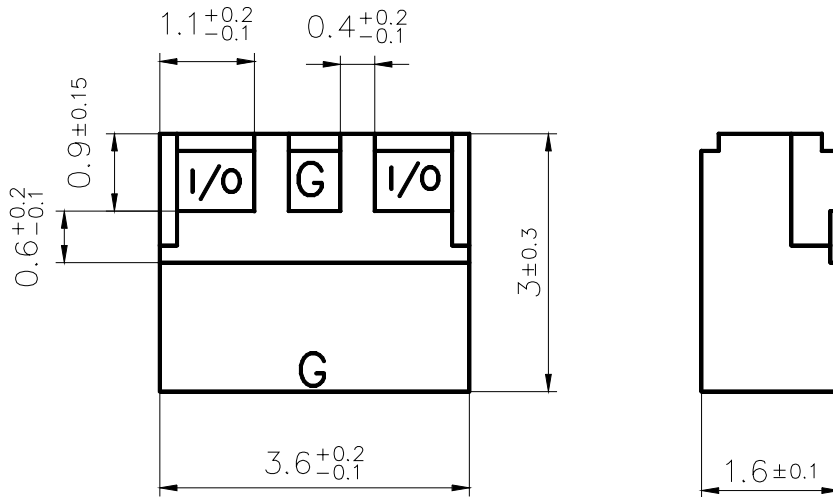
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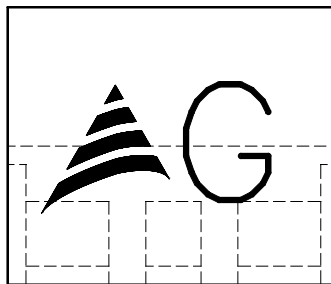
Data Sheet

Component drawing

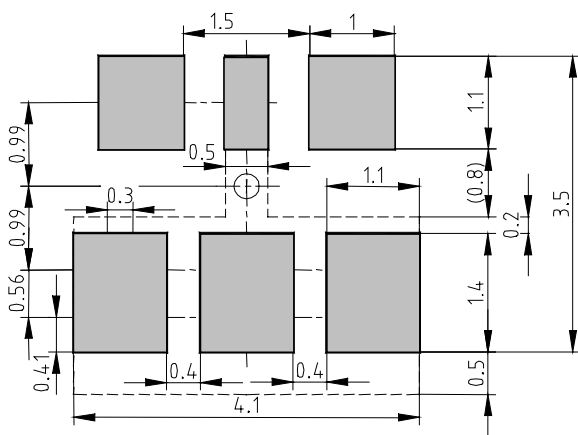


View from below onto the solder terminals and view from beside

Marking



Recommended footprint



I/O Pads must be terminated with 50 Ω characteristic impedance

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Data Sheet

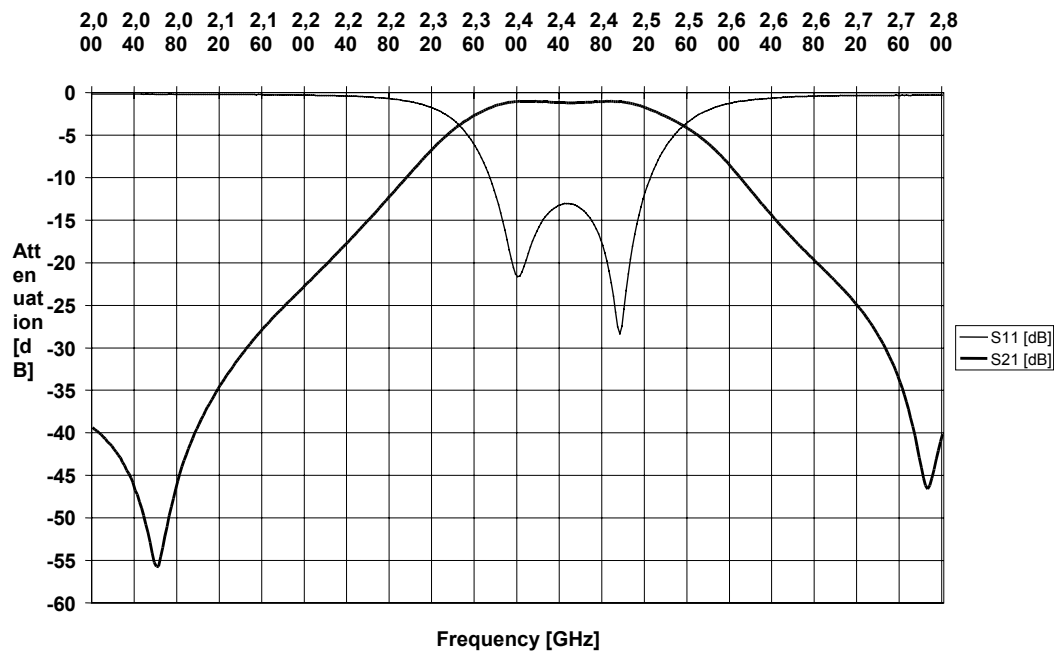
Characteristics

		min.	typ.	max.	
Center frequency	f_c	-	2.45	-	GHz
Insertion loss	α_{IL}		0.8	1.2	dB
Passband	B	100			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$		0.4	0.8	dB
Standing wave ratio	SWR		1.5	2.0	
Impedance	Z		50		Ω
Attenuation					
	at 2150 MHz	25	30		

Maximum ratings

IEC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	T_{op}	- 20 / + 85	°C

Typical passband characteristic



Data Sheet

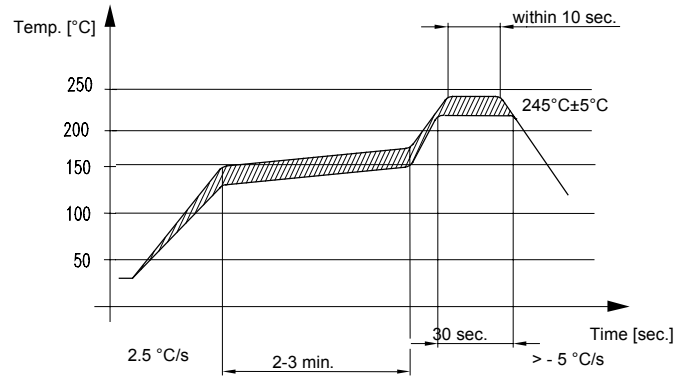
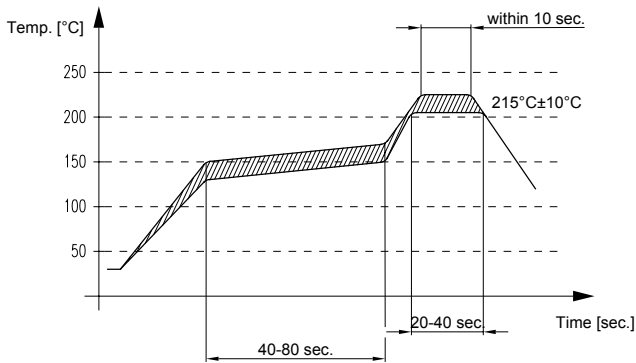
Processing information

- Wettability acc. to IEC 68-2-58: $\geq 75\%$ (after aging)

Soldering Requirements

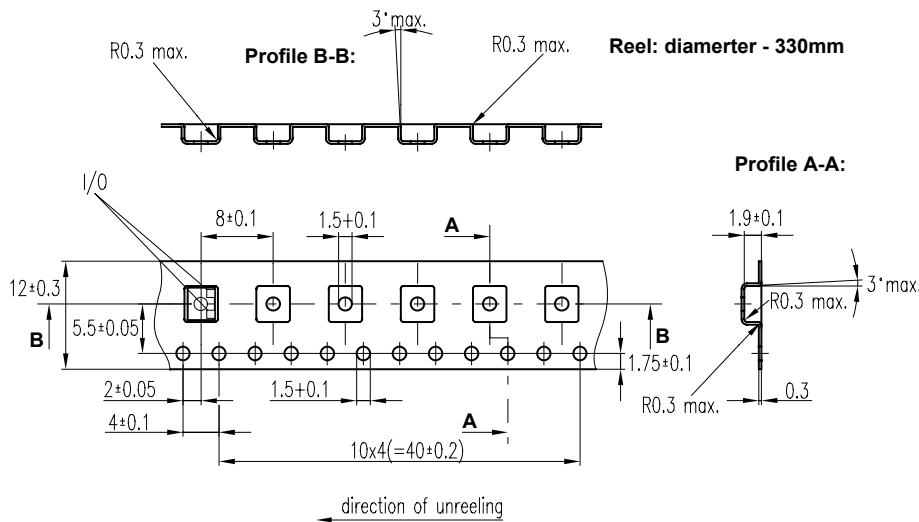
	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

Recommended soldering conditions (infrared):



Delivery mode

- Blister tape acc. to IEC 286-3, PS, grey
- Pieces/tape: 3000



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The information contained in this data sheet describes the type of component and shall not be considered as guaranteed characteristics. Purchase orders are subject to the General Conditions for the Supply of Products and Services of the Electrical and Electronics Industry recommended by the ZVEI (German Electrical and Electronic Manufacturers' Association), unless otherwise agreed.

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